

# Wei He

## List of Publications by Year in descending order

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55

papers

760

citations

566801

15

h-index

580395

25

g-index

56

all docs

56

docs citations

56

times ranked

493

citing authors

#	ARTICLE	IF	CITATIONS
1	Additive-assisted cobalt electrodeposition as surface magnetic coating to enhance the inductance of spiral copper inductors. <i>Surfaces and Interfaces</i> , 2022, 28, 101603.	1.5	2
2	PET Surface Modification with Inkjet-Printing Pd <sup>2+</sup> /Epoxy Resin Solution for Selective Electroless Copper Plating. <i>ACS Applied Electronic Materials</i> , 2022, 4, 149-157.	2.0	7
3	Engineered optoplasmonic core-satellite microspheres for SERS determination of methamphetamine derivative and its precursors. <i>Sensors and Actuators B: Chemical</i> , 2022, 358, 131437.	4.0	10
4	Highly sensitive, flexible and wearable piezoelectric motion sensor based on PT promoted $\beta$ -phase PVDF. <i>Sensors and Actuators A: Physical</i> , 2022, 337, 113415.	2.0	29
5	Direct additive copper plating on polyimide surface with silver ammonia via plasma modification. <i>Applied Surface Science</i> , 2022, 587, 152848.	3.1	7
6	Enhancing peel strength between liquid crystal polymer and copper with plasma treatment, surface oxidation, and silane coating. <i>Journal of Applied Polymer Science</i> , 2022, 139, .	1.3	1
7	Embedded Magnetic Solenoid Inductor Into Organic Packaging Substrate Using Lithographic via Technology for Power Supply Module Integration. <i>IEEE Transactions on Electron Devices</i> , 2022, , 1-7.	1.6	1
8	Polymer-based Cu/Ag composite as seed layer on insulating substrate for copper addition of multi-dimensional conductive patterns. <i>Journal of the Taiwan Institute of Chemical Engineers</i> , 2021, 123, 254-260.	2.7	3
9	Study on fine lines and undercut suppression of printed circuit board prepared by electrolytic etching. <i>Circuit World</i> , 2021, ahead-of-print, .	0.7	0
10	Investigation on Cu-Sn intermetallic compounds growth and signal transmission loss of the diverse copper lines after soldering in printed circuit board. <i>Journal of Materials Science: Materials in Electronics</i> , 2021, 32, 22372-22386.	1.1	3
11	Label-free diagnosis for colorectal cancer through coffee ring-assisted surface-enhanced Raman spectroscopy on blood serum. <i>Journal of Biophotonics</i> , 2020, 13, e201960176.	1.1	52
12	Process, fundamental and application of one-step molten-salt synthesized BaTiO <sub>5</sub> nanorods. <i>Journal of Alloys and Compounds</i> , 2020, 826, 154064.	2.8	5
13	Area-Selective Atomic Layer Deposition of TiN Using Trimethoxy(octadecyl)silane as a Passivation Layer. <i>Langmuir</i> , 2020, 36, 13144-13154.	1.6	7
14	Mechanism of a catalytic silver(I)-complex: assisted electroless deposition of inductance coil on poly(ethylene terephthalate) film. <i>Journal of Materials Science: Materials in Electronics</i> , 2020, 31, 8165-8173.	1.1	1
15	Copolymer of Pyrrole and 1,4-Butanediol Diglycidyl as an Efficient Additive Leveler for Through-Hole Copper Electroplating. <i>ACS Omega</i> , 2020, 5, 4868-4874.	1.6	37
16	Whisker inhibited Sn-Bi alloy coating on copper surface to increase copper bonding strength for signal loss reduction of PCB in high-frequency. <i>Applied Surface Science</i> , 2020, 513, 145718.	3.1	12
17	Optoplasmonic Hybrid Materials for Trace Detection of Methamphetamine in Biological Fluids through SERS. <i>ACS Applied Materials &amp; Interfaces</i> , 2020, 12, 24192-24200.	4.0	43
18	Anisotropic growth of electroless nickel-phosphorus plating on fine sliver lines for L-shape terminal electrode structure of chip inductor. <i>Applied Surface Science</i> , 2019, 496, 143633.	3.1	2

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19	A novel structured spiral planar embedded inductor: Electroless-plating NiCoP alloy on copper coil as magnetic core. Journal of Magnetism and Magnetic Materials, 2019, 489, 165363.	1.0	5
20	Low fractal dimension modified drilling hole wall for PTFE high-frequency board copper plating with plasma treatment. Journal of Applied Polymer Science, 2019, 136, 48052.	1.3	7
21	Communication "Localized Accelerator Pre-Adsorption to Speed Up Copper Electroplating Microvia Filling. Journal of the Electrochemical Society, 2019, 166, D467-D469.	1.3	3
22	Compatible Ag <sup>+</sup> Complex-Assisted Ultrafine Copper Pattern Deposition on Poly(ethylene) Terephthalate (PET) Overlaid with BT Resin. Journal of Materials Science: Materials in Electronics, 2019, 30, 16226-16233.	4.0	36
23	Effect of surface finishing on signal transmission loss of microstrip copper lines for high-speed PCB. Journal of Materials Science: Materials in Electronics, 2019, 30, 16226-16233.	1.1	11
24	Solvent-dependent ultrasonic surface treatment on morphological reconstruction of CuO particles for copper electrodeposition. Applied Surface Science, 2019, 491, 206-215.	3.1	17
25	Direct surface in-situ activation for electroless deposition of robust conductive copper patterns on polyimide film. Journal of the Taiwan Institute of Chemical Engineers, 2019, 97, 450-457.	2.7	9
26	Enhancing adhesion performance of sputtering Ti/Cu film on pretreated composite prepreg for stacking structure of IC substrates. Composites Part B: Engineering, 2019, 158, 400-405.	5.9	27
27	Computational analysis and experimental evidence of two typical levelers for acid copper electroplating. Electrochimica Acta, 2018, 273, 318-326.	2.6	55
28	A composite of epoxy resin/copper(II) acetylacetonate as catalyst of copper addition on insulated substrate. Journal of Materials Science: Materials in Electronics, 2018, 29, 9460-9465.	1.1	4
29	A comparison of typical additives for copper electroplating based on theoretical computation. Computational Materials Science, 2018, 147, 95-102.	1.4	49
30	Enhancing inductance of spiral copper inductor with BaFe <sub>12</sub> O <sub>19</sub> /poly(phenylene oxide) composite as an embedded magnetic core. Composites Part B: Engineering, 2018, 138, 232-242.	5.9	13
31	Enhancing adhesion performance of no-flow prepreg to form multilayer structure of printed circuit boards with plasma-induced surface modification. Surface and Coatings Technology, 2018, 333, 24-31.	2.2	12
32	Preparation and Properties of Cyanate/Epoxy-based Composite with Thermal Conductive Silica Particles. IOP Conference Series: Materials Science and Engineering, 2018, 422, 012003.	0.3	0
33	Electric and thermal performance of poly(phenylene oxide)-based composites with synergetic modification of carbon nanotubes and nanoplatelets. Polymer Composites, 2018, 39, E1920.	2.3	12
34	Direct activation of copper electroplating on conductive composite of polythiophene surface-coated with nickel nanoparticles. Composites Part B: Engineering, 2018, 154, 257-262.	5.9	18
35	Electrochemical investigation of thiourea as corrosion inhibitor for copper in acidic solution. AIP Conference Proceedings, 2017, . . .	0.3	1
36	Incorporation of Tin on copper clad laminate to increase the interface adhesion for signal loss reduction of high-frequency PCB lamination. Applied Surface Science, 2017, 422, 738-744.	3.1	27

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37	Improving wettability of photo-resistive film surface with plasma surface modification for coplanar copper pillar plating of IC substrates. <i>Applied Surface Science</i> , 2017, 411, 82-90.	3.1	13
38	Directly electroless-plating Ni-P thin-film to fabricate magnetic core of integrated inductor for printed circuit board. , 2016, , .		1
39	Fabrication of silver electrically conductive adhesive to apply in through-hole filling for PCB interconnection. <i>Journal of Materials Science: Materials in Electronics</i> , 2016, 27, 9186-9190.	1.1	8
40	Characterization and application of aggregated porous copper oxide flakes for cupric source of copper electrodeposition. <i>Materials Letters</i> , 2015, 139, 458-461.	1.3	10
41	Multiphysics coupling simulation of RDE for PCB manufacturing. <i>Circuit World</i> , 2015, 41, 20-28.	0.7	12
42	Study on brown oxidation process with imidazole group, mercapto group and heterocyclic compounds in printed circuit board industry. <i>Journal of Adhesion Science and Technology</i> , 2015, 29, 1178-1189.	1.4	14
43	Improved Uniformity of Conformal Through-Hole Copper Electrodeposition by Revision of Plating Cell Configuration. <i>Journal of the Electrochemical Society</i> , 2015, 162, D575-D583.	1.3	21
44	Plating Uniformity of Bottom-up Copper Pillars and Patterns for IC Substrates with Additive-assisted Electrodeposition. <i>Electrochimica Acta</i> , 2014, 120, 293-301.	2.6	77
45	Effects of Mn <sup>2+</sup> on the electrical resistance of electrolessly plated Ni-P thin-film and its application as embedded resistor. <i>Journal of Materials Science: Materials in Electronics</i> , 2014, 25, 1341-1347.	1.1	2
46	One step synthesis of silver nanowires used in preparation of conductive silver paste. <i>Journal of Materials Science: Materials in Electronics</i> , 2014, 25, 2929-2933.	1.1	20
47	Effect of MnSO <sub>4</sub> on the Deposition of Electroless Nickel Phosphorus and its Mechanism. <i>Electrochimica Acta</i> , 2014, 127, 276-282.	2.6	7
48	Fabrication of a novel porous Ni-P thin-film using electroless-plating: Application to embedded thin-film resistor. <i>Materials Letters</i> , 2013, 108, 75-78.	1.3	5
49	Research on the effect of inorganic components on brightener in horizontal pulse plating solution by Cyclic Voltammetric Stripping method. , 2012, , .		0
50	Study on manufacturing process of semi-flex Printed Circuit Board using buried material. , 2012, , .		0
51	Preparation and properties of a novel electrically conductive adhesive using a composite of silver nanorods, silver nanoparticles, and modified epoxy resin. <i>Journal of Materials Science: Materials in Electronics</i> , 2012, 23, 108-114.	1.1	34
52	Research on etching blind holes and desmear with plasma. , 2011, , .		2
53	A Novel Nitric Acid Etchant and Its Application in Manufacturing Fine Lines for PCBs. <i>IEEE Transactions on Electronics Packaging Manufacturing</i> , 2010, 33, 25-30.	1.6	4
54	Preparation of ultra-fine copper powder and its application in manufacturing conductive lines by printed electronics technology. , 2009, , .		0

#	ARTICLE	IF	CITATIONS
55	A Catalytic and Interfacing PEDOT:PSS/CuPc Polymerized on Cloth Fiber to Electroâ€Metalize Stretchable Copper Conductive Pattern. Advanced Materials Interfaces, 0, , 2101462.	1.9	2